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**IN THE CLAIMS**

Please amend the claims as follows:

1. (Currently Amended) An alignment weight, comprising:  
a body having a first opposing surface and a second opposing surface ~~surfaces~~; and  
a number of depressions formed in the first opposing surface so as to receive pins of a floating pin field when placed on the floating pin field during connection of the floating pin field to a printed circuit board, wherein selected ones of the number of depressions are configured to receive only one of the pins.
2. (Original) The alignment weight of claim 1, wherein the number of depressions are formed in rows along a perimeter of the body.
3. (Original) The alignment weight of claim 1, wherein the body comprises a material that exhibits substantially no warping during a solder reflow process.
4. (Original) The alignment weight of claim 1, wherein the body further includes a number of holes that pass through a thickness of the body.
5. (Original) The alignment weight of claim 4, wherein the holes are disposed in a center region of the first opposing surface of the body.
6. (Original) The alignment weight of claim 1, wherein the depressions have a diameter at a surface of the body that is greater than a diameter of the depression inside the body.
7. (Currently Amended) An alignment weight, comprising:  
a body having a first opposing surface and a second opposing surface ~~surfaces~~; and  
a plurality of depressions formed in the first opposing surface so as to receive pins of a floating pin field when placed on the floating pin field during connection of the floating pin field to a printed circuit board, wherein each of the plurality of depressions is ~~[[are]]~~ configured to receive only one of the pins of the floating pin field, and wherein the body has a weight sufficient to provide a downward force to secure the pins of the floating pin field in place during a solder

reflow process and to maintain the pins of the floating pin field in a substantially straight-up alignment.

8. (Original) The alignment weight of claim 1, wherein some of the plurality of depressions have an inner diameter smaller than an outer diameter.

9. (Original) The alignment weight of claim 1, wherein some of the plurality of depressions have an interior angle of less than about 90 degrees.

10. (Original) The alignment weight of claim 1, wherein some of the plurality of depressions are substantially circular.

11. (Original) An apparatus, comprising:  
an alignment weight;  
a circuit board; and  
a plurality of pins adjacent the circuit board and a corresponding plurality of depressions in the alignment weight.

12. (Original) The apparatus of claim 11, further comprising:  
a field carrier coupled to the plurality of pins.

13. (Original) The apparatus of claim 11, wherein the alignment weight further includes a plurality of passages that pass through a thickness of the alignment weight.

14. (Currently Amended) The apparatus of claim 13, wherein the plurality of passages is ~~[[are]]~~ disposed in a center region of a first opposing surface of the alignment weight.

15. (Currently Amended) The apparatus of claim 11, wherein the alignment weight comprises a body having a first opposing surface and a second opposing surface ~~surfaces~~, wherein the body has a plurality of passages extending from the first opposing surface to the second opposing surface and located in a center region of the first opposing surface, wherein the corresponding plurality of depressions are disposed in rows about a perimeter of the first opposing surface and configured to receive only one pin of the plurality of pins.

**PRELIMINARY AMENDMENT**

Serial Number: 10/656,559

Filing Date: September 5, 2003

Title: ALIGNMENT WEIGHT FOR FLOATING PIN FIELD DESIGN

Assignee: Intel Corporation

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16. (Original) The apparatus of claim 11, wherein some of the corresponding plurality of depressions have a diameter at a surface of the body that is greater than a diameter of inside the body.